

A SENSOR AND METHOD FOR FABRICATING THE SAME

ABSTRACT

A sensor and method for fabricating a sensor is disclosed that in one embodiment bonds an etched semiconductor substrate wafer (300) to an etched first device wafer (100) comprising a silicon on insulator wafer which is then bonded to a second device wafer (200) comprising a silicon on insulator wafer to create a vented, suspended structure, the flexure of which is sensed by an embedded sensing element (140) to measure differential pressure. In one embodiment, interconnect channels (400) embedded in the sensor facilitate streamlined packaging of the device while accommodating interconnectivity with other devices.

Figure 1.